

Amendment to the Specification

Please replace the paragraph at page 4, lines 1-7, with the following replacement paragraph:

**[0011]** As shown in FIG. 1, a tape 110 of an anisotropic conductive adhesive film is manufactured by patterning a circuit thereon. Thereafter, an anisotropic conductive adhesive 120 is applied on the tape 110 and then connection terminals of a circuit formed on the tape ~~100~~ 110 is connected to bond pads of a chip 130 by using a C4 (controlled collapse chip connection) process.